



**MAX  
245°C**

**MSL  
1**

PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit	ppm		
<b>768 16</b>							<b>276.70</b>			
Alumina Ceramic	Al2O3	1344-28-1	0.8800	0.2435	87.50%	213.0590	77.00%	770000		
	SiO2 (silicon dioxide)	14808-60-7			12.50%	30.4370	11.00%	110000		
					<b>100.00%</b>	<b>243.4960</b>				
Conductor Thick Film	Ag	7440-22-4	0.0068	0.0019	99.00%	1.8627	0.67%	6732		
	Pd	7440-05-3			<b>1.00%</b>	0.0188	0.01%	68		
					<b>100.00%</b>	<b>1.8816</b>				
Resistor Thick Film	RuO2	12036-10-1	0.0079	0.0022	30.00%	0.6558	0.24%	2370		
	PbO	1317-36-8			10.00%	0.2186	0.08%	790		
	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.6558	0.24%	2370		
	B2O3	1303-86-2			30.00%	0.6558	0.24%	2370		
					<b>100.00%</b>	<b>2.1859</b>				
Notch Conductor Thick Film	Ag	7440-22-4	0.0113	0.0031	72.02%	2.2519	0.81%	8138		
	Pd	7440-05-3			4.20%	0.1313	0.05%	475		
	Pt	7440-06-4			23.78%	0.7435	0.27%	2687		
					<b>100.00%</b>	<b>3.1267</b>				
Lead Wire	Cu	7440-50-8	0.0376	0.0104	100.00%	10.4039	3.76%	37600		
Solder	Pb	7439-92-1	0.0376	0.0104	<b>100.00%</b>	<b>10.4039</b>				
	Sn	7440-31-5			90.00%	9.3635	3.38%	33840		
					10.00%	1.0404	0.38%	3760		
					<b>100.00%</b>	<b>10.4039</b>				
Covercoat	TiO2	13463-67-7	0.0188	0.0052	50.00%	2.6010	0.94%	9400		
	Phenolic Resin	55185-45-0			25.00%	1.3005	0.47%	4700		
	Epoxy Resin	25068-38-6			25.00%	1.3005	0.47%	4700		
	Sum				1.0000 part weight	0.2767	<b>100.00%</b>	<b>5.2020</b>		
						0.2767				
		<b>Totals:</b>		<b>0.2767</b>		<b>276.70</b>	<b>100.00%</b>	<b>1000000</b>		